



1. Number of layers - 2
2. Board size - 80mm x 58mm. Tolerance - +/- 0.15mm
3. Board thickness - 1.6mm +/-10% (see stack-up data)
4. Material - FR-4 High Tg, copper thickness is 35um (1oz)
5. Solder Mask shall be applied on two sides, Green, Liquid. Solder mask mis-registration +/-0.05mm. No overlap permitted on SMD lands. Solder Mask is in accordance with IPC-SM-840 D, Class H
6. Silkscreen - white, TOP side only
7. Type of finish - ENIG
8. Electrical test shall be performed on both sides
9. Min. plated hole size - 0.3mm
10. Min. annular ring - 0.15mm
11. Min. trace width/clearance - 0.2mm
12. Impedance control - No
13. This data also exists in CAD gerber format. In case of any discrepancies gerber data prevails.

Symbol	Count	Hole Size	Plated	Hole Tolerance
□	5	0.80	Plated	
☆	2	2.00	Non-Plated	
✧	4	2.80	Plated	
▽	173	0.30	Plated	

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS SURFACE FINISH: TOLERANCES:				FINISH:				DEBURR AND BREAK SHARP EDGES		DO NOT SCALE DRAWING		REVISION		4.4			
	NAME		SIGNATURE		DATE					TITLE: LEDS Board Fabrication Drawing							
DRAW	Y.Alsharik				2024.07.10												
CHK'D	A.Kovalenko				2024.07.10												
APPV'D																	
MFG																	
QA																	
							MATERIAL:			DWG N0.				A3			
							WEIGHT:			SCALE 1:1				SHEET 1 OF 1			